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Part Number: [0702474051](#)
Status: **Active**
Overview: C-Grid® Products
Description: 2.54mm Pitch C-Grid® Header, Dual Row, Low Profile, Right Angle, Shrouded, 40 Circuits, 0.38µm Gold (Au) Selective Plating, Tin (Sn) PC Tail Plating

Documents:

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Drawing \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E29179

General

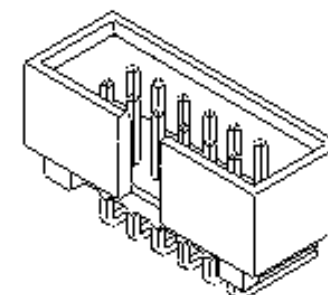
Product Family PCB Headers
 Series [70247](#)
 Application Signal, Wire-to-Board
 Overview [C-Grid® Products](#)
 Product Name C-Grid®
 UPC 822348488476

Physical

Breakaway No
 Circuits (Loaded) 40
 Circuits (maximum) 40
 Color - Resin Black
 Durability (mating cycles max) 50
 First Mate / Last Break No
 Flammability 94V-0
 Glow-Wire Compliant No
 Guide to Mating Part No
 Keying to Mating Part None
 Lock to Mating Part None
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin Polyester
 Net Weight 5.317/g
 Number of Rows 2
 Orientation Right Angle
 PC Tail Length 3.05mm
 PCB Locator No
 PCB Retention None
 PCB Thickness - Recommended 1.60mm
 Packaging Type Tray
 Pitch - Mating Interface 2.54mm
 Pitch - Termination Interface 2.54mm
 Plating min - Mating 0.381µm
 Plating min - Termination 1.905µm
 Polarized to Mating Part Center Slot
 Shrouded Fully
 Stackable No
 Temperature Range - Operating -55°C to +120°C
 Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 2.5A



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Yes -ED/39/2015 (15 June 2015)
 C,C'-azodi(formamide)
 tricosafuorododecanoic acid
 heptacosafuorotetradecanoic acid
 methoxyacetic acid
 1,2-diethoxyethane
 hencosafuoroundecanoic acid
 sodium peroxometaborate
 pentacosafuorotridecanoic acid
 3-ethyl-2-methyl-2-(3-methylbutyl)-1,3-oxazolidi
 Disodium tetraborate
 Boric acid
 Trixylyl phosphate
 4-(1,1,3,3-tetramethylbutyl)phenol, ethoxylated
 Methylhexahydrophthalic anhydride
 Sodium perborate; perboric acid, sodium salt
 furan
 dinoseb (ISO)
 Acetamide, N-methyl-propylene oxide
 diethyl sulphate
 #,#-Bis[4-(dimethylamino)phenyl]-4(phenylamino)
 Diboron-trioxide

China RoHS

Voltage - Maximum 250V DC

Solder Process Data

Duration at Max. Process Temperature (seconds) 010
Lead-free Process Capability WAVE
Max. Cycles at Max. Process Temperature 001
Process Temperature max. C 235

Material Info

Reference - Drawing Numbers

Sales Drawing SDA-70247-**-00-04

4,4'-bis(dimethylamino)-4''-(methylamino)trityl
1,2-bis(2-methoxyethoxy)ethane
N,N,N',N'-tetramethyl-4,4'-methyldianiline
4,4'-bis(dimethylamino)benzophenone formamide
Boric acid, disodium salt, hydrate
Trichloroethylene
Silicic acid (H₂Si₂O₅), barium salt (1:1), lead-

Halogen-Free Status

Not Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com
Please visit the [Contact Us](#) section for any non-product compliance questions.

China ROHS Green Image
ELV Not Relevant

Search Parts in this Series

[70247 Series](#)

Mates With

[70450 SL™](#) Crimp Housing, [70058 SL™](#) Crimp Terminal

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